COMPLIANT



### Vishay Semiconductors

# Half Bridge IGBT Power Module, 600 V, 50 A



PRODUCT SUMMARY						
$V_{CES}$	600 V					
I <sub>C</sub> at T <sub>C</sub> = 80 °C	50 A					
V <sub>CE(on)</sub> (typical) at I <sub>C</sub> = 50 A, 25 °C	1.65 V					
Speed	8 kHz to 30 kHz					
Package	INT-A-PAK					
Circuit	Half bridge					

#### **FEATURES**

- Low V<sub>CE(on)</sub> trench IGBT technology
- 5 µs short circuit capability
- V<sub>CE(on)</sub> with positive temperature coefficient
- Maximum junction temperature 175 °C
- · Low inductance case
- · Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>

#### **TYPICAL APPLICATIONS**

- UPS (Uninterruptable Power Supply)
- · Electronic welders
- Switching mode power supplies

#### **DESCRIPTION**

Vishay's IGBT power module provides ultra low conduction loss as well as short circuit ruggedness. It is designed for applications such as UPS and SMPS.

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Collector to emitter voltage	V <sub>CES</sub>		600	V	
Gate to emitter voltage	$V_{GES}$		± 20	V	
Collector current I <sub>C</sub>		T <sub>C</sub> = 25 °C	85		
	T <sub>C</sub> = 80 °C	50			
Pulsed collector current	I <sub>CM</sub> <sup>(1)</sup>	t <sub>p</sub> = 1 ms	100	Α	
Diode continuous forward current	I <sub>F</sub>	T <sub>C</sub> = 80 °C	50		
Diode maximum forward current	I <sub>FM</sub> <sup>(1)</sup>	t <sub>p</sub> = 1 ms	100		
Maximum power dissipation	P <sub>D</sub>	T <sub>J</sub> = 175 °C	208	W	
Short circuit withstand time	t <sub>SC</sub>	T <sub>C</sub> = 125 °C	5	μs	
RMS isolation voltage	V <sub>ISOL</sub>	f = 50 Hz, t = 1 min	4000	V	

#### Note

(1) Repetitive rating: pulse width limited by maximum junction temperature.

IGBT ELECTRICAL SPECIFICATIONS (T <sub>C</sub> = 25 °C unless otherwise noted)							
PARAMETER	SYMBOL	SYMBOL TEST CONDITIONS MIN. TYP		TYP.	MAX.	UNITS	
Collector to emitter breakdown voltage	V <sub>(BR)CES</sub>	T <sub>J</sub> = 25 °C	600	-	-		
Collector to emitter voltage	V	$V_{GE} = 15 \text{ V}, I_{C} = 50 \text{ A}, T_{J} = 25 \text{ °C}$	-	1.65	2.10		
	V <sub>CE(on)</sub>	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 50 A, T <sub>J</sub> = 175 °C	-	2.05	-	V	
Gate to emitter threshold voltage	V <sub>GE(th)</sub>	$V_{CE} = V_{GE}$ , $I_C = 1.4$ mA, $T_J = 25$ °C	4.0	4.9	6.5		
Collector cut-off current	I <sub>CES</sub>	$V_{CE} = V_{CES}$ , $V_{GE} = 0$ V, $T_{J} = 25$ °C	-	-	1.0	mA	
Gate to emitter leakage current	I <sub>GES</sub>	$V_{GE} = V_{GES}$ , $V_{CE} = 0$ V, $T_{J} = 25$ °C	-	-	400	nA	



SWITCHING CHARACTERISTICS	3					
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on delay time	t <sub>d(on)</sub>		-	58	-	ns ns
Rise time	t <sub>r</sub>		-	31	-	
Turn-off delay time	t <sub>d(off)</sub>	$V_{CC} = 300 \text{ V}, I_{C} = 50 \text{ A}, R_{g} = 3.3 \Omega, V_{GE} = \pm 15 \text{ V}, T_{J} = 25 ^{\circ}\text{C}$	-	80	-	
Fall time	t <sub>f</sub>	$V_{GE} = \pm 15 \text{ V}, T_{J} = 25 \text{ °C}$	-	100	-	
Turn-on switching loss	E <sub>on</sub>		-	0.41	-	
Turn-off switching loss	E <sub>off</sub>		-	0.42	-	- mJ
Turn-on delay time	t <sub>d(on)</sub>		-	64	-	- ns
Rise time	t <sub>r</sub>		-	37	-	
Turn-off delay time	t <sub>d(off)</sub>	$V_{CC} = 300 \text{ V, } I_{C} = 50 \text{ A, } R_{g} = 3.3 \Omega, \\ V_{GE} = \pm 15 \text{ V, } T_{J} = 125 \text{ °C}$	-	90	-	
Fall time	t <sub>f</sub>		-	117	-	
Turn-on switching loss	E <sub>on</sub>		-	0.69	-	ml
Turn-off switching loss	E <sub>off</sub>		-	0.69	-	mJ
Input capacitance	C <sub>ies</sub>		-	3.03	-	
Output capacitance	C <sub>oes</sub>	$V_{GE} = 0 \text{ V}, V_{CE} = 30 \text{ V}, f = 1.0 \text{ MHz}$	-	0.25	-	nF
Reverse transfer capacitance	C <sub>res</sub>		-	0.09	-	
SC data	I <sub>SC</sub>	$t_p \leq 5~\mu s,~V_{GE} = 15~V,~T_J = 125~^{\circ}C,\\ V_{CC} = 360~V,~V_{CEM} \leq 600~V$	-	450	-	Α
Stray inductance	L <sub>CE</sub>		-	-	30	nH
Module lead resistance, terminal to chip	R <sub>CC'+EE'</sub>		-	0.75	-	mΩ

<b>DIODE ELECTRICAL SPECIFICATIONS</b> (T <sub>C</sub> = 25 °C unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDIT	TEST CONDITIONS		TYP.	MAX.	UNITS
Forward voltage	V	I <sub>F</sub> = 50 A	T <sub>J</sub> = 25 °C	-	1.35	1.75	V
	$V_{F}$		T <sub>J</sub> = 125 °C	-	1.37	-	
Dovorgo recovery charge	0		$T_J = 25  ^{\circ}C$	-	2.3	-	
Reverse recovery charge	Q <sub>rr</sub>		T <sub>J</sub> = 125 °C	-	4.3	-	μC
Peak reverse recovery current		$I_{rr} \qquad I_{F} = 50 \text{ A, } V_{R} = 300 \text{ V,} \\ R_{G} = 3.3 \Omega \\ V_{GE} = -15 \text{ V}$	T <sub>J</sub> = 25 °C	-	33	-	^
Peak reverse recovery current	¹rr		T <sub>J</sub> = 125 °C	-	58	-	A
Reverse recovery energy E <sub>re</sub>	_		T <sub>J</sub> = 25 °C	-	0.56	-	m l
	⊏rec		T <sub>J</sub> = 125 °C	-	1.11	-	mJ

THERMAL AND MECHANICAL SPECIFICATIONS							
PARAMETER		SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction temperature	range	TJ		-	-	175	°C
Storage temperature range		T <sub>Stg</sub>		-40	-	125	ç
Junction to case	IGBT	R <sub>thJC</sub>		-	-	0.72	
per ½ module	Diode	PthJC		-	-	1.02	K/W
Case to sink (Conductive greas	se applied)	R <sub>thCS</sub>		-	0.05	-	
Mounting torque			Power terminal screw: M5	2.5 to 5.0		Nm	
			Mounting screw: M6		3.0 to 5.0	)	INIII
Weight			Weight of module	-	150	-	g

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## Vishay Semiconductors

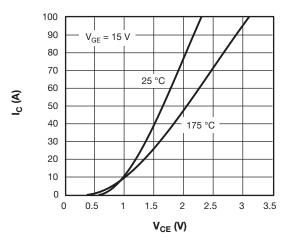


Fig. 1 - IGBT Typical Output Characteristics

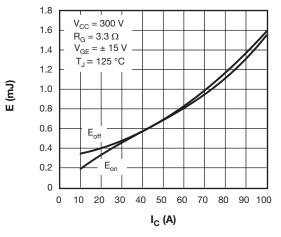


Fig. 2 - IGBT Transfer Characteristics

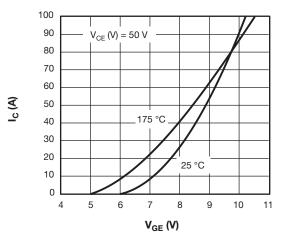


Fig. 3 - IGBT Switching Loss vs. I<sub>C</sub>

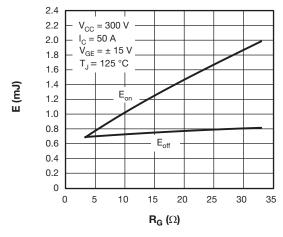
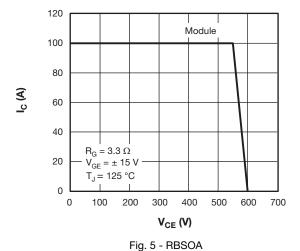


Fig. 4 - IGBT Switching Loss vs. R<sub>G</sub>



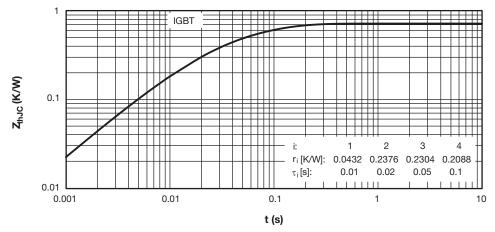


Fig. 6 - IGBT Transient Thermal Impedance

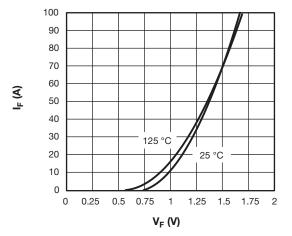


Fig. 7 - Diode Forward Characteristics

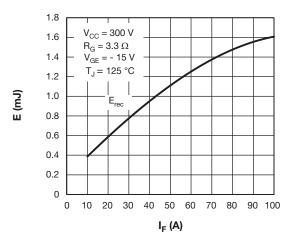


Fig. 8 - Diode Switching Loss vs. I<sub>F</sub>

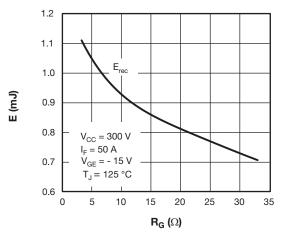


Fig. 9 - Diode Switching Loss vs. R<sub>G</sub>

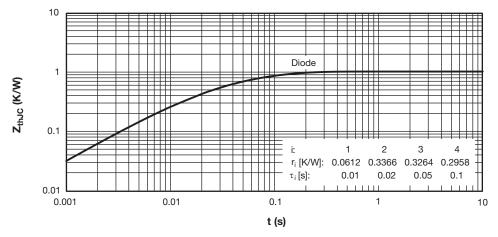
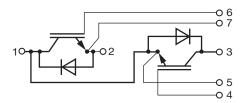


Fig. 10 - Diode Transient Thermal Impedance

#### **CIRCUIT CONFIGURATION**

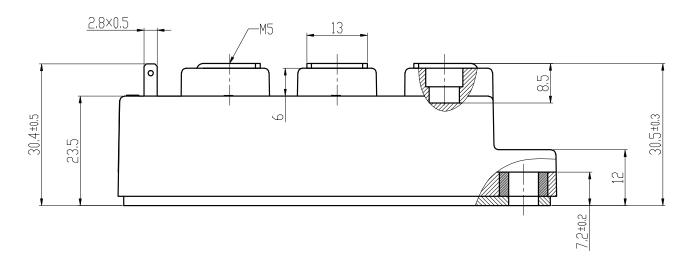


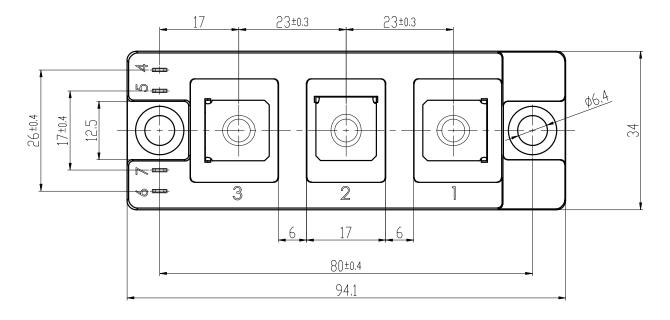
LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95524			



### **INT-A-PAK**

#### **DIMENSIONS** in millimeters (inches)







### **Legal Disclaimer Notice**

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